



**DEFENSE LOGISTICS AGENCY**  
 LAND AND MARITIME  
 POST OFFICE BOX 3990  
 COLUMBUS, OH 43218-3990

June 9, 2011

Ms. Lucy Garvin  
 DDi Toronto Corp.  
 8150 Sheppard Avenue East  
 Scarborough, Ontario  
 Canada, M1B 5K2

Dear Ms. Garvin:

RE: Acceptable Capability Verification Inspection, MIL-PRF-31032, FSC 5998, January 1, 2009 through December 31 2010 Reporting Period; CAGE Code 3AF82; VQE-11-022677

Your biannual Capability Verification Inspection report has been reviewed. The data successfully demonstrates your ability to manufacture printed wiring boards to an adjusted set of qualifications capabilities. Therefore, DDi Toronto's qualification is reissued under the current issue of the Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032 /1 & /2 and your listing will be revised as indicated below on the Qualified Manufacturers List QML-31032.

<b>MANUFACTURER NAME &amp; ADDRESS</b>  Ms. Lucy Garvin DDi Toronto Corp. 8150 Sheppard Avenue East Scarborough, Ontario Canada, M1B 5K2	<b>PLANT LOCATIONS</b>  8150 Sheppard Avenue East Scarborough, Ontario Canada, M1B 5K2 & 2020 Ellesmere Rd. Scarborough, Ontario Canada, M1H 2Z8	<b>CAGE CODE: 3AF82</b>  <b>CONTACT: Ms. Lucy Garvin</b> <b>PHONE #: (416) 208-2100</b> <b>FAX #: (416) 208-2196</b> <b>EMAIL: lgarvin@ddiglobal.com</b>
<b>CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:</b>		<b>QUALIFICATION LETTER:</b>
<b>MIL-PRF-31032/1, /2</b>  Panel Size 18" X 24" Max. Board Thickness .088" Cu Foil Weight ¼ oz. to 2 oz. Max/Min Plated Hole Size / .0098" (drilled, mechanical) Aspect Ratio 8.4:1 Max. Number of Layers 18 Min. Conductor Width .0037" Min. Conductor Spacing .0028" Part Mounting SM, THM, MIX Base Material GF (Woven E-Glass, Epoxy resin) Finish System HASL, ENIG Hole Preparation Chemical Desmear, Plasma Etchback Copper Plating Acid Copper Solder Resist LPI Hole Wall Conductive Coating Electroless Copper Controlled Impedance Characteristics (+/- 10%) Differential (+/- 10%) Alternate Construction Blind Vias, Sequential Lamination, Foil Lamination, Buried Vias, Microvias Hole Fill / Via Plug Non-conductive Epoxy Hole Fill / Via Plug, Copper Hole Fill		VQE-04-006240, VQE-08-015407, VQE-09-018857 VQE-11-022676

CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:	QUALIFICATION LETTER:
<b>MIL-PRF-31032/1, /2</b> Panel Size 18" X 24" Max. Board Thickness .093" Cu Foil Weight ¼ oz. to 2 oz. Max/Min Plated Hole Size / .0091" (drilled, mechanical) Aspect Ratio 9.6:1 Max. Number of Layers 20 Min. Conductor Width .004" Min. Conductor Spacing .003" Part Mounting SM, THM, MIX Base Material GI (Woven E-Glass, Polyimide Resin) Finish System HASL Hole Preparation Chemical Desmear, Plasma Etchback Copper Plating Acid Copper Solder Resist LPI Hole Wall Conductive Coating Electroless Copper Controlled Impedance Characteristics (+/- 10%) Differential (+/- 10%) Alternate Construction Blind Vias, Sequential Lamination, Foil Lamination, Buried Vias, Microvias Hole Fill / Via Plug Non-conductive Epoxy Hole Fill / Via Plug, Copper Hole Fill	VQE-04-006240, VQE-08-015407, VQE-09-018857 VQE-11-022676

Your next CVI report should cover the period from January 1, 2011 through December 2012. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during Periodic Conformance Inspection (PCI) or Capability Verification Inspection (CVI) testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Lowell Sherman, (614) 692-0627.

Sincerely,



RAYMOND L. KOLONCHUK  
Chief  
Electronic Devices Branch

cc:  
NDQAR Ont-Prairies